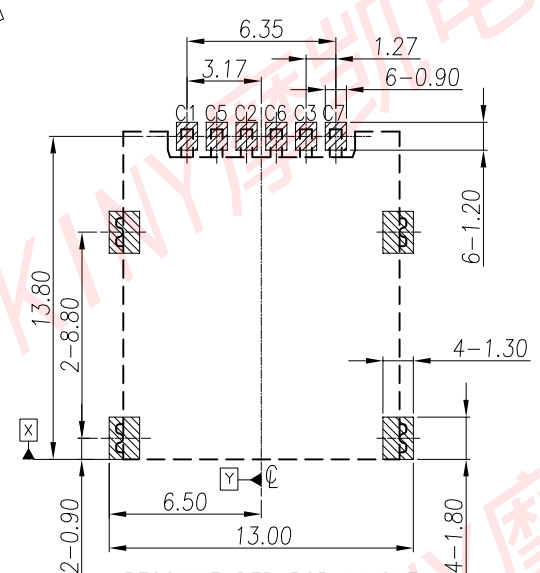
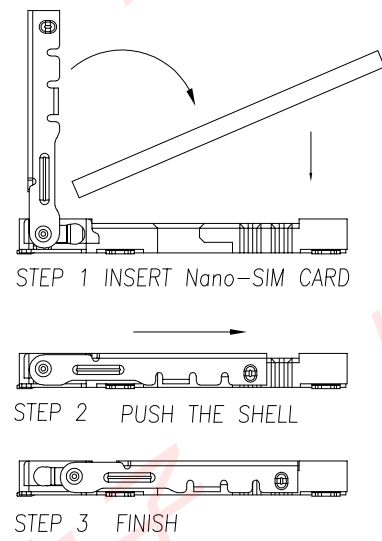
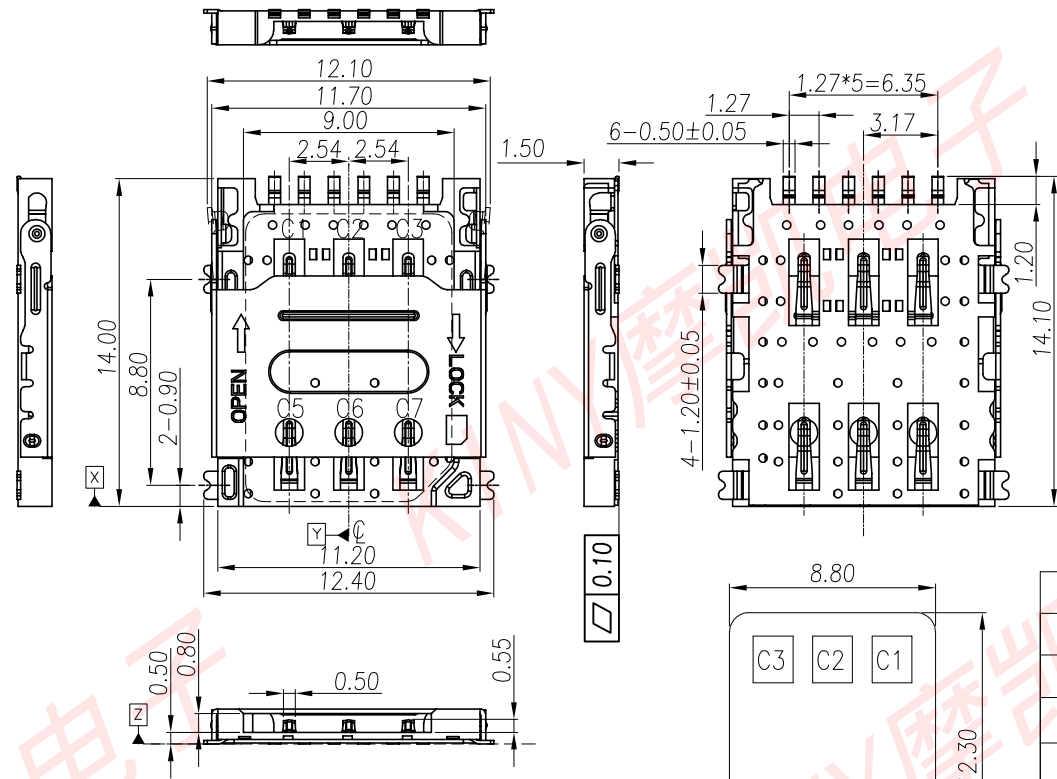
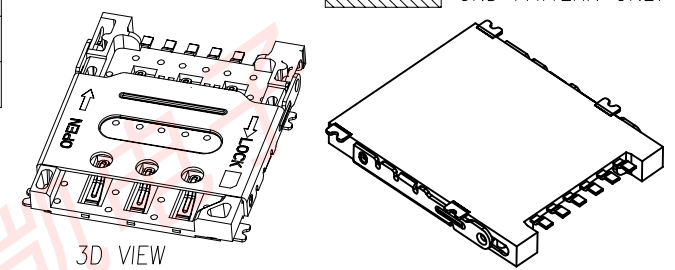
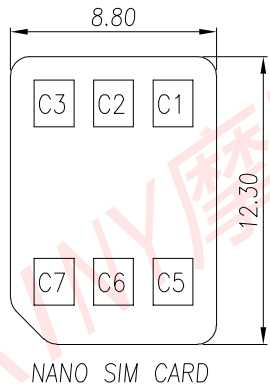


\* 所有原料材质, 生产制程, 电镀必须符合HF要求



SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



NOTE:

- Material:
  - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
  - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.15±0.02mm)
  - 1-3 Cover: SUS301-H T=0.20±0.03mm
- Plating:
  - Contact terminal: Contact area: Gold 1u" Min. Solder area: Gold 0.8u" Min. Underplating: Ni overall 50u" Min.
- Specification:
  - 3-1. CONTACT RESISTANCE: 50 Milliohms Max
  - 3-2. INSULATION RESISTANCE: 1,000 Megohms Min.
  - 3-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.
  - 3-4. OPERATION TEMPERATURE RANGE: -25°C~+70°C
  - 3-5. DURABILITY: 3000 CYCLES
- Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
- Part Must Comply Taisol HF WD-3-I-091 Specification.
- Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

A	----	NEW RELEASE	ping	2015.10.05
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				

	<b>东莞市摩凯电子有限公司</b>			
	DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : NANO SIM 1.50H 掀盖式卡座	DRAWING: Jack	DATE: 2015.10.05
	DIMENSION TOLERANCE X.X: ± 0.30 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : NS150-T1150-01-W	CHECK: Alex	DATE: 2015.10.05
		DRAWING NO. : D-NS150-T1150-01-W	APPROVED: Alex	DATE: 2015.10.05
		SCALE: 1:1	DWG ID: C D	REV.: A
				PAGE: 1 OF 1